Very Low Supply Current 3-Pin Microprocessor Reset Monitor

The MAX803/NCP803 is a cost–effective system supervisor circuit designed to monitor $V_{\rm CC}$ in digital systems and provide a reset signal to the host processor when necessary. No external components are required.

The reset output is driven active within 10 µsec of V_{CC} falling through the reset voltage threshold. Reset is maintained active for a timeout period which is trimmed by the factory after V_{CC} rises above the reset threshold. The MAX803/NCP803 has an open drain active—low \overline{RESET} output. Both devices are available in SOT–23 and SC–70 packages.

The MAX803/NCP803 is optimized to reject fast transient glitches on the V_{CC} line. Low supply current of 0.5 μA (V_{CC} = 3.2 V) make these devices suitable for battery powered applications.

Features

- Precision V_{CC} Monitor for 1.5 V, 1.8 V, 2.5 V, 3.0 V, 3.3 V, and 5.0 V Supplies
- Precision Monitoring Voltages from 1.2 V to 4.9 V Available in 100 mV Steps
- Four Guaranteed Minimum Power–On Reset Pulse Width Available (1 ms, 20 ms, 100 ms, and 140 ms)
- RESET Output Guaranteed to $V_{CC} = 1.0 \text{ V}$
- Low Supply Current
- V_{CC} Transient Immunity
- No External Components
- Wide Operating Temperature: -40°C to 105°C
- Pb-Free Packages are Available

Typical Applications

- Computers
- Embedded Systems
- Battery Powered Equipment
- Critical Microprocessor Power Supply Monitoring

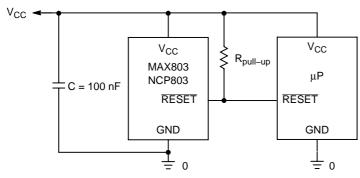


Figure 1. Typical Application Diagram



ON Semiconductor®

http://onsemi.com

MARKING DIAGRAM



SOT-23 (TO-236) CASE 318





SC-70 (SOT-323) CASE 419

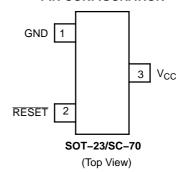


xxx = Specific Device Code

M = Date Code

■ = Pb-Free Package (Note: Microdot may be in either location)

PIN CONFIGURATION



ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 7 of this data sheet.

DEVICE MARKING INFORMATION

See general marking information in the device marking section on page 7 of this data sheet.

PIN DESCRIPTION

Pin No.	Symbol	Description
1	GND	Ground
2	RESET	$\overline{\text{RESET}} \text{ output remains low while V}_{\text{CC}} \text{ is below the reset voltage threshold, and for a reset timeout period after V}_{\text{CC}} \text{ rises above reset threshold.}$
3	V _{CC}	Supply Voltage: C = 100 nF is recommended as a bypass capacitor between V _{CC} and GND.

ABSOLUTE MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Power Supply Voltage (V _{CC} to GND)	V _{CC}	-0.3 to 6.0	V
RESET Output Voltage (CMOS)		-0.3 to (V _{CC} + 0.3)	V
Input Current, V _{CC}		20	mA
Output Current, RESET		20	mA
dV/dt (V _{CC})		100	V/μsec
Thermal Resistance, Junction-to-Air (Note 1) SOT-23 SC-70	03/	301 314	°C/W
Operating Junction Temperature Range	TJ	-40 to +105	°C
Storage Temperature Range	T _{stg}	-65 to +150	°C
Lead Temperature (Soldering, 10 Seconds)	T _{sol}	+260	°C
ESD Protection Human Body Model (HBM): Following Specification JESD22–A114 Machine Model (MM): Following Specification JESD22–A115		2000 200	V
Latchup Current Maximum Rating: Following Specification JESD78 Class II Positive Negative		200 200	mA

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

2. The maximum package power dissipation limit must not be exceeded.

$$P_D = \frac{T_{J(max)} - T_A}{R_{\theta JA}} \quad \text{with } T_{J(max)} = 150^{\circ}C$$

^{1.} This based on a 35x35x1.6mm FR4 PCB with 10mm² of 1 oz copper traces under natural convention conditions and a single component characterization.

ELECTRICAL CHARACTERISTICS $T_A = -40^{\circ}C$ to $+105^{\circ}C$ unless otherwise noted. Typical values are at $T_A = +25^{\circ}C$. (Note 3)

Characteristic	Symbol	Min	Тур	Max	Unit
V _{CC} Range					V
$T_A = 0$ °C to +70°C		1.0	_	5.5	
$T_A = -40$ °C to +105°C		1.2	_	5.5	
Supply Current	Icc				μΑ
$V_{CC} = 3.3 \text{ V}$					
$T_A = -40$ °C to +85°C		-	0.5	1.2	
$T_A = 85^{\circ}C$ to $+105^{\circ}C$		-	_	2.0	
$V_{CC} = 5.5 \text{ V}$					
$T_A = -40^{\circ}\text{C to } +85^{\circ}\text{C}$		_	0.8	1.8	
$T_A = 85^{\circ}C \text{ to } +105^{\circ}C$		-	_	2.5	
Reset Threshold (V _{in} Decreasing) (Note 4)	V _{TH}				V
MAX803SQ463/NCP803SN463					
$T_A = +25^{\circ}C$		4.56	4.63	4.70	
$T_A = -40^{\circ}\text{C} \text{ to } +85^{\circ}\text{C}$		4.51	_	4.75	
$T_A = +85^{\circ}C$ to $+105^{\circ}C$		4.40	_	4.88	
MAX803SQ438/NCP803SN438					
$T_A = +25$ °C		4.31	4.38	4.45	
$T_A = -40^{\circ}C$ to $+85^{\circ}C$		4.27		4.49	
$T_A = +85^{\circ}C \text{ to } +105^{\circ}C$		4.16		4.60	
MAX803SQ308/NCP803SN308					
$T_A = +25^{\circ}C$		3.04	3.08	3.11	
$T_A = -40$ °C to +85°C		3.00	_	3.15	
$T_A = +85^{\circ}C \text{ to } +105^{\circ}C$		2.92	_	3.23	
MAX803SQ293/NCP803SN293					
$T_A = +25^{\circ}C$		2.89	2.93	2.96	
$T_A = -40^{\circ}\text{C to } +85^{\circ}\text{C}$		2.85	_	3.00	
$T_A = +85^{\circ}C \text{ to } +105^{\circ}C$		2.78	_	3.08	
NCP803SN263					
$T_A = +25^{\circ}C$		2.59	2.63	2.66	
$T_A = -40^{\circ}$ C to +85°C		2.55	2.00	2.70	
$T_A = +85^{\circ}C \text{ to } +105^{\circ}C$		2.50	_	2.76	
		2.00		2.70	
NCP803SN232 $T_A = +25^{\circ}C$		2.29	2.32	2.35	
$T_A = -40^{\circ}\text{C}$ to +85°C		2.29	2.32	2.33	
$T_A = +85^{\circ}\text{C to } +65^{\circ}\text{C}$ $T_A = +85^{\circ}\text{C to } +105^{\circ}\text{C}$		2.20	_	2.45	
• • • • • • • • • • • • • • • • • • • •		2.20	_	2.45	
NCP803SN160		4.50	4.00	4.00	
$T_A = +25^{\circ}C$		1.58	1.60	1.62	
$T_A = -40^{\circ}\text{C to } +85^{\circ}\text{C}$		1.56 1.52	_	1.64	
$T_A = +85^{\circ}C$ to $+105^{\circ}C$		1.52	_	1.68	
MAX803SN120, MAX803SQ120		1 10	1.20	4.00	
$T_A = +25^{\circ}C$ $T_A = -40^{\circ}C$ to +85°C		1.18 1.17	1.20	1.22 1.23	
$T_A = +85^{\circ}\text{C} \text{ to } +65^{\circ}\text{C}$ $T_A = +85^{\circ}\text{C} \text{ to } +105^{\circ}\text{C}$		1.17	_	1.26	
Detector Voltage Threshold Temperature Coefficient		_	30	-	ppm/°C
V _{CC} to Reset Delay V _{CC} = V _{TH} to (V _{TH} – 100 mV)		_	10	_	μsec
Reset Active TimeOut Period (Note 5)	too	 			msec
MAX803SN(Q)293D1	t _{RP}	1.0	_	3.3	111360
MAX803SN(Q)293D2		20	_	66	
MAX803SN(Q)293D3		100	_	330	
MAX803SN(Q)293		140	_	460	
RESET Output Voltage Low	V _{OL}	_		0.3	V
$V_{CC} = V_{TH} - 0.2 V$					1
$1.6 \text{ V} \leq \text{V}_{TH} \leq 2.0 \text{ V}, \text{I}_{SINK} = 0.5 \text{ mA}$					1
$2.1 \text{ V} \leq \text{V}_{TH} \leq 4.0 \text{ V}, \text{I}_{SINK} = 1.2 \text{ mA}$					
$4.1 \text{ V} \leq \text{V}_{TH} \leq 4.9 \text{ V}, \text{I}_{SINK} = 3.2 \text{ mA}$					
		l		 	
RESET Leakage Current	I _{LEAK}	_	_	1	μΑ

Production testing done at T_A = 25°C, over temperature limits guaranteed by design.
 Contact your ON Semiconductor sales representative for other threshold voltage options.
 Contact your ON Semiconductor sales representative for timeout options availability for other threshold voltage options.

TYPICAL OPERATING CHARACTERISTICS

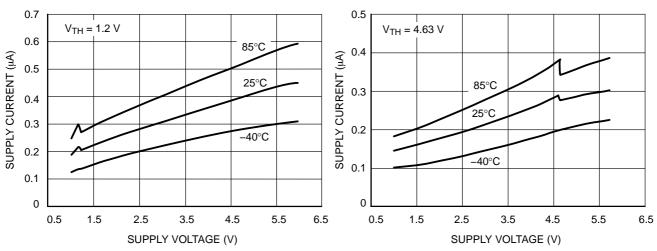


Figure 2. Supply Current vs. Supply Voltage

Figure 3. Supply Current vs. Supply Voltage

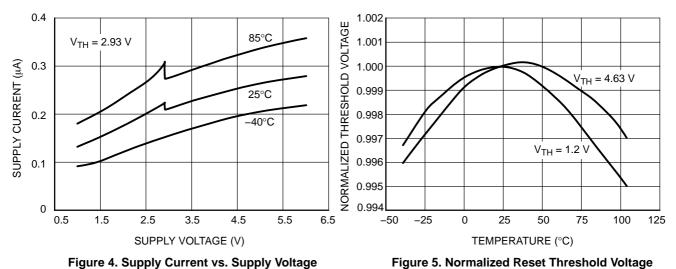


Figure 4. Supply Current vs. Supply Voltage

0.5

0.4

0.3

0.2

0.1

-50

-25

SUPPLY CURRENT (µA)

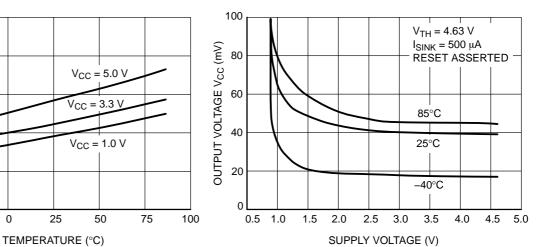
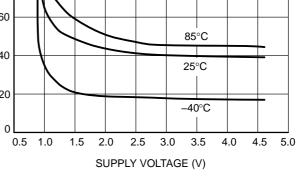


Figure 6. Supply Current vs. Temperature



vs. Temperature

Figure 7. Output Voltage Low vs. Supply Voltage

TYPICAL OPERATING CHARACTERISTICS

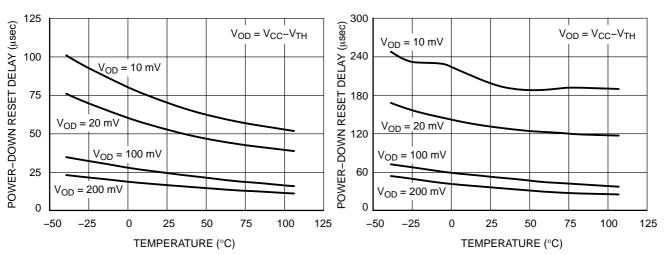


Figure 8. Power–Down Reset Delay vs. Temperature and Overdrive ($V_{TH} = 1.2 \text{ V}$)

Figure 9. Power–Down Reset Delay vs. Temperature and Overdrive (V_{TH} = 4.63 V)

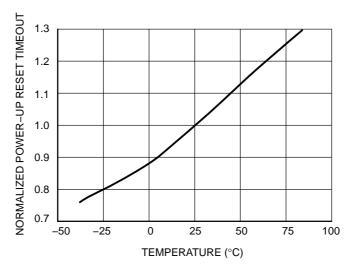
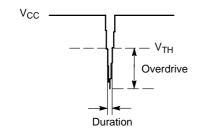


Figure 10. Normalized Power–Up Reset vs. Temperature

APPLICATIONS INFORMATION

V_{CC} Transient Rejection

The MAX803/NCP803 series provides accurate V_{CC} monitoring and reset timing during power–up, power–down, and brownout/sag conditions, and rejects negative–going transients (glitches) on the power supply line. Figure 11 shows the maximum transient duration vs. maximum negative excursion (overdrive) for glitch rejection. Any combination of duration and overdrive which lies under the curve will not generate a reset signal. Combinations above the curve are detected as a brownout or power–down. Typically, transient that goes 100 mV below the reset threshold and lasts 5.0 μ s or less will not cause a reset pulse. Transient immunity can be improved by adding a capacitor in close proximity to the V_{CC} pin of the MAX803



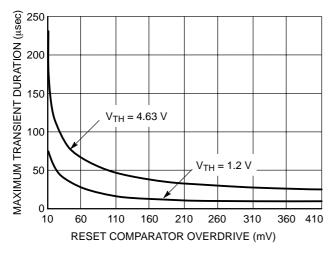
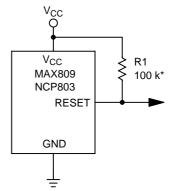


Figure 11. Maximum Transient Duration vs. Overdrive for Glitch Rejection at 25°C

RESET Signal Integrity During Power–Down

The MAX803/NCP803 \overline{RESET} output is valid to $V_{CC} = 1.0 \text{ V}$. Below this voltage the output becomes an "open circuit" and does not sink current. This means CMOS logic inputs to the Microprocessor will be floating at an undetermined voltage. Most digital systems are completely shutdown well above this voltage. However, in situations where \overline{RESET} must be maintained valid to $V_{CC} = 0 \text{ V}$, since

the NCP803/MAX803 has Open–Drain and active–low output, it typically uses a pullup resistor. With this device, RESET will most likely not maintain an active condition, but will drift to a non–active level due to the pullup resistor and the reduced sinking capability of the open–drain device. Therefore, this device is not recommended for applications where the $\overline{\text{RESET}}$ pin is required to be valid down to $V_{CC} = 0 \text{ V}$.



*Assume High-Z Reset Input to Microprocessor

Figure 12. RESET Signal Integrity

MAX803 RESET Output Allows Use With Two Power Supplies

In numerous applications the pullup resistor place on the \overline{RESET} output is connected to the supply voltage monitored by the IC. Nevertheless, a different supply voltage can also power this output and so level—shift from the monitored supply to reset the microprocessor. However, if the NCP803/MAX803's supply goes blew 1 V, the \overline{RESET} output ability to sink current will decrease and the result is a high state on the pin even though the supply's IC is under the threshold level. This occurs at a V_{CC} level that depends on the R_{pullup} value and the voltage which is connected.

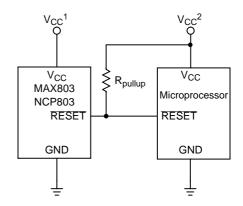


Figure 13. MAX803 RESET Output with Two Supplies

ORDERING, MARKING AND THRESHOLD INFORMATION

Part Number	Vth* (V)	Time out** (ms)	Description	Marking	Package	Shipping [†]
NCP803SN160T1	1.60	140–460		SCQ	SOT23-3	
NCP803SN160T1G	1.60	140–460		SCQ	SOT23-3 (Pb-Free)	
NCP803SN232T1	2.32	140–460		SQR	SOT23-3	
NCP803SN232T1G	2.32	140–460		SQR	SOT23-3 (Pb-Free)	
NCP803SN263T1	2.63	140–460		SQC	SOT23-3	
NCP803SN263T1G	2.63	140–460		SQC	SOT23-3 (Pb-Free)	
NCP803SN293T1	2.93	140–460		SQD	SOT23-3	
NCP803SN293T1G	2.93	140–460		SQD	SOT23-3 (Pb-Free)	
NCP803SN308T1	3.08	140–460		SQE	SOT23-3	
NCP803SN308T1G	3.08	140–460		SQE	SOT23-3 (Pb-Free)	
NCP803SN438T1	4.38	140–460		SQF	SOT23-3	
NCP803SN438T1G	4.38	140–460		SQF	SOT23-3 (Pb-Free)	
NCP803SN463T1	4.63	140–460		SQG	SOT23-3	
NCP803SN463T1G	4.63	140–460		SQG	SOT23-3 (Pb-Free)	
NCP803SN120T1G	1.20	140–460	Open Drain RESET	SSW	SOT23-3 (Pb-Free)	3000 / Tape & Reel
NCP803SN293D1T1G	2.93	1–3.3		SSX	SOT23-3 (Pb-Free)	
NCP803SN293D2T1G	2.93	20–66		SSY	SOT23-3 (Pb-Free)	
NCP803SN293D3T1G	2.93	100–330		SSZ	SOT23-3 (Pb-Free)	
MAX803SQ120T1G	1.20	140–460		ZV	SC70-3 (Pb-Free)	
MAX803SQ293T1G	2.93	140–460		ZW	SC70-3 (Pb-Free)	
MAX803SQ308T1G	3.08	140–460		ZX	SC70-3 (Pb-Free)	
MAX803SQ438T1G	4.38	140–460		ZY	SC70-3 (Pb-Free)	
MAX803SQ463T1G	4.63	140–460		ZZ	SC70-3 (Pb-Free)	
MAX803SQ293D1T1G	2.93	1–3.3		YA	SC70-3 (Pb-Free)	
MAX803SQ293D2T1G	2.93	20–66		YB	SC70-3 (Pb-Free)	
MAX803SQ293D3T1G	2.93	100–330		YC	SC70-3 (Pb-Free)	

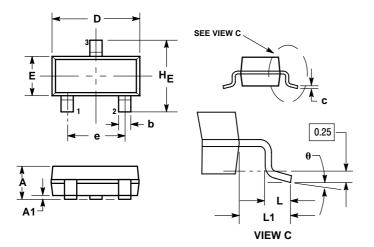
[†]For information on tape and reel specifications,including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

*Contact your ON Semiconductor sales representative for other threshold voltage options.

**Contact your ON Semiconductor sales representative for timeout options availability for other threshold voltage options.

PACKAGE DIMENSIONS

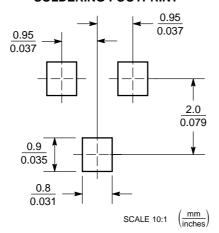
SOT-23 (TO236) CASE 318-08 **ISSUE AN**



- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF PACE MATERIAL
- BASE MATERIAL. 318–01 THRU –07 AND –09 OBSOLETE, NEW STANDARD 318-08.

	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	0.89	1.00	1.11	0.035	0.040	0.044
A1	0.01	0.06	0.10	0.001	0.002	0.004
b	0.37	0.44	0.50	0.015	0.018	0.020
С	0.09	0.13	0.18	0.003	0.005	0.007
D	2.80	2.90	3.04	0.110	0.114	0.120
E	1.20	1.30	1.40	0.047	0.051	0.055
е	1.78	1.90	2.04	0.070	0.075	0.081
L	0.10	0.20	0.30	0.004	0.008	0.012
L1	0.35	0.54	0.69	0.014	0.021	0.029
HE	2.10	2.40	2.64	0.083	0.094	0.104

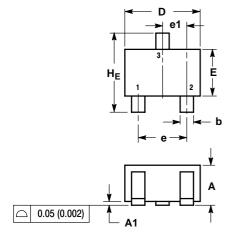
SOLDERING FOOTPRINT*

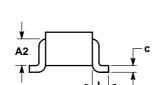


^{*}For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS

SC-70 (SOT-323) CASE 419-04 ISSUE M



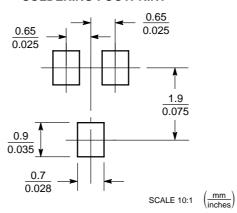


NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI
- 2. CONTROLLING DIMENSION: INCH.

	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	0.80	0.90	1.00	0.032	0.035	0.040
A1	0.00	0.05	0.10	0.000	0.002	0.004
A2		0.7 REF			0.028 REF	
b	0.30	0.35	0.40	0.012	0.014	0.016
С	0.10	0.18	0.25	0.004	0.007	0.010
D	1.80	2.10	2.20	0.071	0.083	0.087
E	1.15	1.24	1.35	0.045	0.049	0.053
е	1.20	1.30	1.40	0.047	0.051	0.055
e1	0.65 BSC			0.026 BSC		
L	0.425 REF			0.017 REF		
HE	2.00	2.10	2.40	0.079	0.083	0.095

SOLDERING FOOTPRINT*



*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

ON Semiconductor and are registered trademarks of Semiconductor Components Industries, LLC (SCILLC). SCILLC reserves the right to make changes without further notice to any products herein. SCILLC makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does SCILLC assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. "Typical" parameters which may be provided in SCILLC data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. SCILLC does not convey any license under its patent rights nor the rights of others. SCILLC products are not designed, intended, or authorized for use a components in systems intended for surgical implant into the body, or other application in which the failure of the SCILLC product could create a situation where personal injury or death may occur. Should Buyer purchase or use SCILLC products for any such unintended or unauthorized application, Buyer shall indemnify and hold SCILLC and its officers, employees, subsidiaries, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that SCILLC was negligent regarding the design or manufacture of the part. SCILLC is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor P.O. Box 61312, Phoenix, Arizona 85082–1312 USA Phone: 480–829–7710 or 800–344–3860 Toll Free USA/Canada Fax: 480–829–7709 or 800–344–3867 Toll Free USA/Canada Email: orderlit@onsemi.com

N. American Technical Support: 800–282–9855 Toll Free USA/Canada

Japan: ON Semiconductor, Japan Customer Focus Center 2–9–1 Kamimeguro, Meguro–ku, Tokyo, Japan 153–0051 Phone: 81–3–5773–3850

ON Semiconductor Website: http://onsemi.com

Order Literature: http://www.onsemi.com/litorder

For additional information, please contact your local Sales Representative.

ПОСТАВКА ЭЛЕКТРОННЫХ КОМПОНЕНТОВ

многоканальный

Общество с ограниченной ответственностью «МосЧип» ИНН 7719860671 / КПП 771901001 Адрес: 105318, г.Москва, ул.Щербаковская д.3, офис 1107

Данный компонент на территории Российской Федерации Вы можете приобрести в компании MosChip.

Для оперативного оформления запроса Вам необходимо перейти по данной ссылке:

http://moschip.ru/get-element

Вы можете разместить у нас заказ для любого Вашего проекта, будь то серийное производство или разработка единичного прибора.

В нашем ассортименте представлены ведущие мировые производители активных и пассивных электронных компонентов.

Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

На всех этапах разработки и производства наши партнеры могут получить квалифицированную поддержку опытных инженеров.

Система менеджмента качества компании отвечает требованиям в соответствии с ГОСТ Р ИСО 9001, ГОСТ РВ 0015-002 и ЭС РД 009

Офис по работе с юридическими лицами:

105318, г. Москва, ул. Щербаковская д. 3, офис 1107, 1118, ДЦ «Щербаковский»

Телефон: +7 495 668-12-70 (многоканальный)

Факс: +7 495 668-12-70 (доб.304)

E-mail: info@moschip.ru

Skype отдела продаж:

moschip.ru moschip.ru_6 moschip.ru_4 moschip.ru_9